



**THE DATASHEET OF  
SN75LVCP600DRFT**



# SN75LVCP600 6-Gbps SATA PCB and Cable Equalizer

## 1 Features

- SATA Express Support
- Selectable Equalization and De-Emphasis
- Hot Plug Capable
- Receiver Detect and OOB Support
- Multirate Operation: 1.5 Gbps, 3 Gbps, and 6 Gbps
- Suitable to Receive 6-Gbps Data Over Up to 40 Inches (1 Meter) of FR4
- Compensates Up to 14-dB Loss on the Receive Side and 1.2-dB Loss on the Transmit Side at 3 GHz
- Integrated Output Squelch
- Auto Low Power Feature Lowers Power by > 90%
  - < 100 mW (Active Mode, Typical)
  - < 11 mW (Auto Low Power Mode, Typical)
- Single 3.3-V Supply
- High Protection Against ESD Transient
  - HBM: 6 kV
  - CDM: 1.5 kV
- Ultra-Small Footprint: 2 mm x 2 mm WSON Package

## 2 Applications

- Notebooks
- Desktops
- Docking Stations
- Servers
- Workstations

## 3 Description

The SN75LVCP600 is a versatile single channel, SATA Express signal conditioner supporting data rates up to 6 Gbps. The device supports SATA Gen 1, 2, and 3 specifications as well as PCIe 1.0, 2.0, and 3.0. The SN75LVCP600 operates from a single 3.3-V supply and has 100-Ω line termination with self-biasing feature, making the device suitable for AC coupling. The inputs incorporate an out-of-band (OOB) detector, which automatically squelches the output when the input differential voltage falls below threshold while maintaining a stable common-mode voltage. The device is also designed to handle spread spectrum clocking (SSC) transmission per SATA standard.

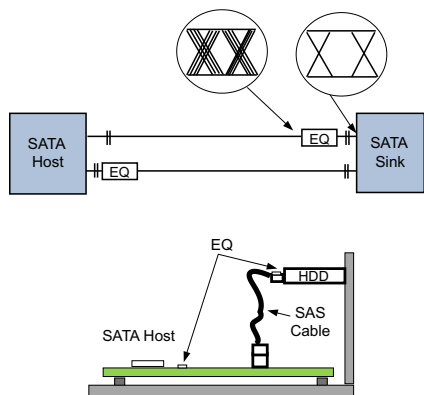
The SN75LVCP600 handles interconnect losses at its input with selectable equalization settings that can be programmed to match the loss in the channel. For data rates of 3 Gbps and lower the SN75LVCP600 equalizes signals for a span of up to 50 inches of FR4 board material. For data rates of 8 Gbps the device compensates up to 40 in of FR4 material. The equalization level is controlled by the setting of the signal control pin EQ.

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN75LVCP600	WSON (8)	2.00 mm x 2.00 mm

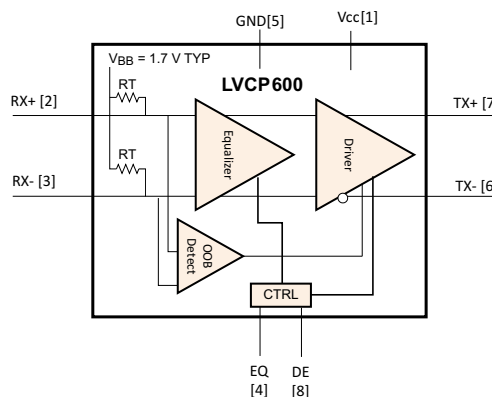
(1) For all available packages, see the orderable addendum at the end of the data sheet.

### Typical Application



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### Data Flow Block Diagram



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## 4 Revision History

Changes from Original (December 2010) to Revision A	Page
• Added Device Information table, ESD Ratings table, <i>Feature Description</i> section, <i>Device Functional Modes</i> , <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section. ....	<b>1</b>
• Changed RX+ from I, VML to I, CML in <i>Pin Functions</i> table .....	<b>3</b>
• Changed Noninverting and inverting VML differential inputs to Noninverting and inverting CML differential inputs in the <i>Pin Functions</i> table Description .....	<b>3</b>
• Changed RX- from I, VML to I, CML in <i>Pin Functions</i> table .....	<b>3</b>
• Changed TX+ from I, VML to O, VML in <i>Pin Functions</i> table .....	<b>3</b>
• Changed TX- from I, VML to O, VML in <i>Pin Functions</i> table .....	<b>3</b>
• Added <i>Parameter Measurement Information</i> section .....	<b>9</b>
• Changed RX to Rx0. in <a href="#">Figure 7</a> .....	<b>9</b>

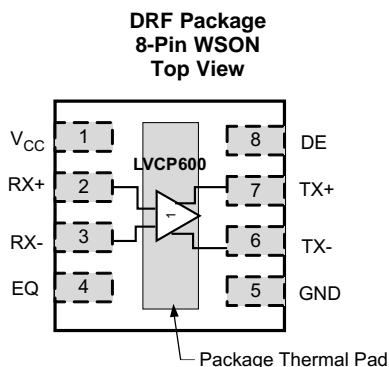
## 5 Description (continued)

Two de-emphasis levels can be selected on the transmit side to provide 0 dB or 1.2 dB of additional high-frequency loss compensation at the output.

The device is hot-plug capable<sup>(1)</sup> preventing device damage under device *hot*-insertion such as async signal plug and removal, unpowered plug and removal, powered plug and removal, or surprise plug and removal.

(1) Requires use of AC coupling capacitors at differential inputs and outputs.

## 6 Pin Configuration and Functions



### Pin Functions

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
<b>HIGH SPEED DIFFERENTIAL I/O</b>			
RX+	2	I	Noninverting and inverting CML differential inputs. These pins are tied to an internal voltage bias by dual termination resistor circuit.
RX-	3	I	
TX+	7	O	Noninverting and inverting VML differential outputs. These pins are tied to an internal voltage bias by dual termination resistor circuit.
TX-	6	O	
<b>CONTROL PINS</b>			
EQ	4	I	Selects equalization settings per <a href="#">Table 1</a> . Internally tied to GND.
DE	8	I	Selects de-emphasis settings per <a href="#">Table 1</a> . Internally tied to GND.
<b>POWER</b>			
V <sub>CC</sub>	1	P	Positive supply must be 3.3 V ±10%
GND	5	G	Supply ground

(1) G = Ground, I = Input, O = Output, P = Power

## 7 Specifications

### 7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
Supply voltage, $V_{CC}$ <sup>(2)</sup>		-0.5	4	V
Voltage	Differential I/O	-0.5	4	V
	Control I/O	-0.5	$V_{CC} + 0.5$	
Storage temperature, $T_{stg}$		-65	150	°C

- (1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any conditions beyond those indicated under [Recommended Operating Conditions](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to network ground pin.

### 7.2 ESD Ratings

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins <sup>(1)</sup>	±6000	V
		Charged device model (CDM), per JEDEC specification JESD22-C101, all pins <sup>(2)</sup>	±1500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 7.3 Recommended Operating Conditions

typical values for all parameters are at  $V_{CC} = 3.3$  V and  $T_A = 25^\circ\text{C}$ ; all temperature limits are specified by design

		MIN	TYP	MAX	UNIT
$V_{CC}$	Supply voltage	3	3.3	3.6	V
	Coupling capacitor	75	100	200	nF
$T_A$	Operating free-air temperature	0		85	°C

### 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		SN75LVCP600	UNIT
		DRF (WSON)	
		8 PINS	
$R_{\theta JA}$	Junction-to-ambient thermal resistance	97.8	°C/W
$R_{\theta Jctop}$	Junction-to-case (top) thermal resistance	81.9	°C/W
$R_{\theta JB}$	Junction-to-board thermal resistance	65.6	°C/W
$\Psi_{JT}$	Junction-to-top characterization parameter	1.3	°C/W
$\Psi_{JB}$	Junction-to-board characterization parameter	65.6	°C/W
$R_{\theta Jcbot}$	Junction-to-case (bottom) thermal resistance	19.1	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

### 7.5 Electrical Characteristics

over recommended operating conditions (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
<b>DEVICE PARAMETERS</b>						
$I_{CCMax-s}$	Active mode supply current	EQ/DE = NC, K28.5 pattern at 6 Gbps, $V_{ID} = 700$ mV <sub>pp</sub>		29	40	mA
$I_{CCPS}$	Auto power save mode $I_{CC}$	When auto low power conditions are met		3.3	5.9	mA
	Maximum data rate			6		Gbps

## Electrical Characteristics (continued)

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>OOB</b>						
V <sub>OOB</sub>	Input OOB threshold	F = 750 MHz	50	70	90	mV <sub>pp</sub>
D <sub>VdiffOOB</sub>	OOB differential delta				25	mV
D <sub>VCMOOB</sub>	OOB common-mode delta				50	mV
<b>CONTROL LOGIC</b>						
V <sub>IH</sub>	High-level input voltage	For all control pins	1.4			V
V <sub>IL</sub>	Low-level input voltage				0.5	V
V <sub>INHYS</sub>	Input hysteresis			115		mV
I <sub>IH</sub>	High-level input current	V <sub>IH</sub> = V <sub>CC</sub> (DE/EQ)			20	μA
I <sub>IL</sub>	Low-level input current	V <sub>IL</sub> = 0 V (DE/EQ)			10	μA
<b>RECEIVER AC/DC</b>						
Z <sub>DIFFRX</sub>	Differential input impedance		85	100	115	Ω
Z <sub>SERX</sub>	Single-ended input impedance		40			Ω
V <sub>CMRX</sub>	Common-mode voltage			1.7		V
R <sub>LDiffRX</sub>	Differential mode return loss (RL)	f = 150 MHz to 300 MHz	18	26		dB
		f = 300 MHz to 600 MHz	14	22		
		f = 600 MHz to 1.2 GHz	10	17		
		f = 1.2 GHz to 2.4 GHz	8	12		
		f = 2.4 GHz to 3 GHz	3	11		
R <sub>XDiffRLSlope</sub>	Differential mode RL slope	f = 300 MHz to 6 GHz (see <a href="#">Figure 7</a> )		-13		dB/dec
R <sub>LCMRX</sub>	Common-mode return loss	f = 150 MHz to 300 MHz	5	9.4		dB
		f = 300 MHz to 600 MHz	5	17		
		f = 600 MHz to 1.2 GHz	2	18		
		f = 1.2 GHz to 2.4 GHz	1	9.9		
		f = 2.4 GHz to 3 GHz	1	8.6		
V <sub>diffRX</sub>	Differential input voltage PP	f = 1.5 GHz and 3 GHz	120		1600	mV <sub>pp</sub>
I <sub>B RX</sub>	Impedance balance	f = 150 MHz to 300 MHz	30	41		dB
		f = 300 MHz to 600 MHz	30	41		
		f = 600 MHz to 1.2 GHz	20	34		
		f = 1.2 GHz to 2.4 GHz	10	24		
		f = 2.4 GHz to 3 GHz	10	26		
		f = 3 GHz to 5 GHz	4	18		
		f = 5 GHz to 6.5 GHz	4	18		
<b>TRANSMITTER AC/DC</b>						
Z <sub>diffTX</sub>	Pair differential impedance		85	100	122	Ω
Z <sub>SETX</sub>	Single-ended input impedance		40			Ω
V <sub>Txtrans</sub>	Sequencing transient voltage	Transient voltages on the serial data bus during power sequencing (lab load)	-1.2	0.3	1.2	V
R <sub>LDiffTX</sub>	Differential mode return loss	f = 150 MHz to 300 MHz	13	22		dB
		f = 300 MHz to 600 MHz	8	21		
		f = 600 MHz to 1.2 GHz	6	19		
		f = 1.2 GHz to 2.4 GHz	6	14		
		f = 2.4 GHz to 3 GHz	3	14		
T <sub>XDiffRLSlope</sub>	Differential mode RL slope	f = 300 MHz to 3 GHz (see <a href="#">Figure 7</a> )		-13		dB/dec

## Electrical Characteristics (continued)

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
RL <sub>CMTX</sub>	Common-mode return loss	f = 150 MHz to 300 MHz	5	20		dB
		f = 300 MHz to 600 MHz	5	16		
		f = 600 MHz to 1.2 GHz	2	13		
		f = 1.2 GHz to 2.4 GHz	1	8		
		f = 2.4 GHz to 3 GHz	1	8		
IB <sub>TX</sub>	Impedance balance	f = 150 MHz to 300 MHz	30	38		dB
		f = 300 MHz to 600 MHz	30	38		
		f = 600 MHz to 1.2 GHz	20	33		
		f = 1.2 GHz to 2.4 GHz	10	25		
		f = 2.4 GHz to 3 GHz	10	25		
		f = 3 GHz to 5 GHz	4	21		
	f = 5 GHz to 6.5 GHz	4	21			
Diff <sub>VppTX</sub>	Differential output voltage swing	f = 3 GHz (under no interconnect loss)	400	650	900	mV <sub>pp</sub>
VCM <sub>AC_TX</sub>	TX AC CM voltage	At 1.5 GHz		15	50	mV <sub>pp</sub>
		At 3 GHz		10	26	dBmV (rms)
		At 6 GHz		12	30	dBmV (rms)
VCM <sub>TX</sub>	Common-mode voltage		1.7		V	
<b>TRANSMITTER JITTER<sup>(1)</sup></b>						
DJ <sub>TX</sub>	Residual deterministic jitter	VID = 500 mV <sub>pp</sub> , UI = 333 ps, K28.5 control character, see <a href="#">Figure 8</a>		0.12	0.19	UI <sub>pp</sub>
RJ <sub>TX</sub>	Random jitter	VID = 500 mV <sub>pp</sub> , UI = 333 ps, K28.7 control character, see <a href="#">Figure 8</a>		1	2	ps-rms
DJ <sub>TX</sub>	Residual deterministic jitter	VID = 500 mV <sub>pp</sub> , UI = 167 ps, K28.5 control character, see <a href="#">Figure 8</a>		0.12	0.34	UI <sub>pp</sub>
RJ <sub>TX</sub>	Random jitter	VID = 500 mV <sub>pp</sub> , UI = 167 ps, K28.7 control character, see <a href="#">Figure 8</a>		0.95	2	ps-rms

(1)  $T_J = (14.1 \times RJ_{SD} + DJ)$  where  $RJ_{SD}$  is one standard deviation value of RJ Gaussian distribution. Jitter measurement is at the SATA connector and includes jitter generated at the package connection on the printed-circuit board, and at the board interconnect as shown in [Figure 8](#).

## 7.6 Timing Requirements

			MIN	TYP	MAX	UNIT
<b>DEVICE PARAMETERS</b>						
t <sub>PDelay</sub>	Propagation delay	Measured using K28.5 pattern (see <a href="#">Figure 1</a> )		275	350	ps
AutoLP <sub>ENTRY</sub>	Auto low power entry time	Electrical idle at input (see <a href="#">Figure 3</a> )		11		μs
AutoLP <sub>EXIT</sub>	Auto low power exit time	After first signal activity (see <a href="#">Figure 3</a> )		33	50	ns
<b>OOB</b>						
t <sub>OOB1</sub>	OOB mode enter	See <a href="#">Figure 2</a>		1	5	ns
t <sub>OOB2</sub>	OOB mode exit	See <a href="#">Figure 2</a>		1	5	ns
<b>RECEIVER AC/DC</b>						
t <sub>20-80RX</sub>	Rise and fall time	Rise times and fall times measured between 20% and 80% of the signal. SATA 3 Gbps speed measured 1" from device pin.	62		75	ps
t <sub>skewRX</sub>	Differential skew	Difference between the single-ended mid-point of the RX+ signal rising and falling edge, and the single-ended mid-point of the RX- signal falling and rising edge.			30	ps
<b>TRANSMITTER AC/DC</b>						

Timing Requirements (continued)

			MIN	TYP	MAX	UNIT
$t_{20-80TX}$	Rise and fall time	Rise times and fall times measured between 20% and 80% of the signal. At 3 Gbps under no load conditions measured at the pin.	44	58	85	ps
$t_{skewTX}$	Differential skew	Difference between the single-ended mid-point of the TX+ signal rising edge and falling edge, and the single-ended mid-point of the TX- signal falling edge and rising edge, $D1, D0 = V_{CC}$		2	15	ps
$t_{xR/Fimb}$	TX rise and fall imbalance	At 3 Gbps		6%	20%	
$t_{xAmpImb}$	TX amplitude imbalance			1%	10%	
<b>TRANSMITTER JITTER</b>						
	Rise and Fall time		46.5%	47.5%	48.3%	
	Rise and Fall mismatch		1.5%	3%		

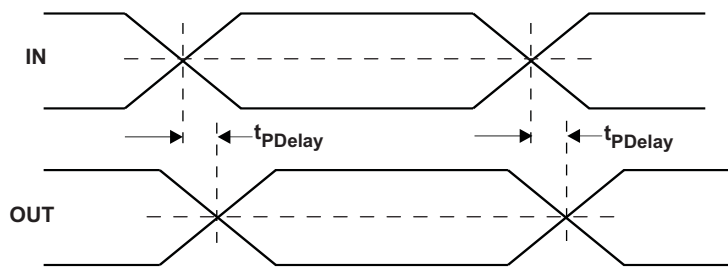


Figure 1. Propagation Delay Timing Diagram

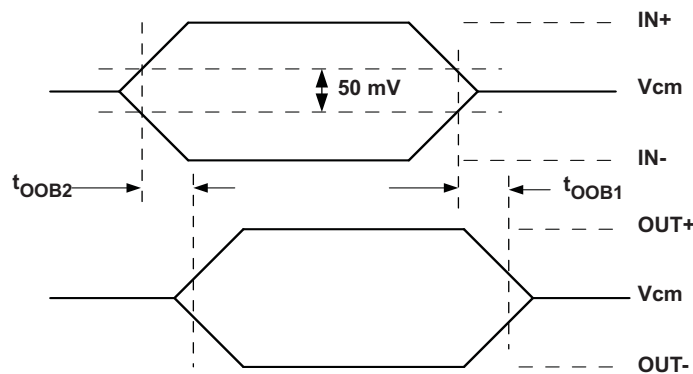


Figure 2. OOB Enter and Exit Timing

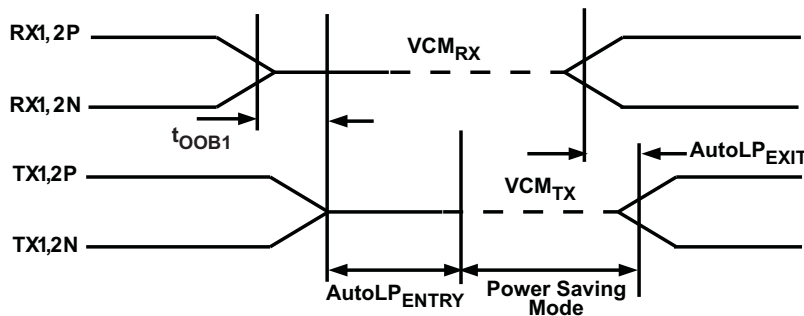


Figure 3. Auto Low Power Mode Entry and Exit Timing

### 7.7 Typical Characteristics

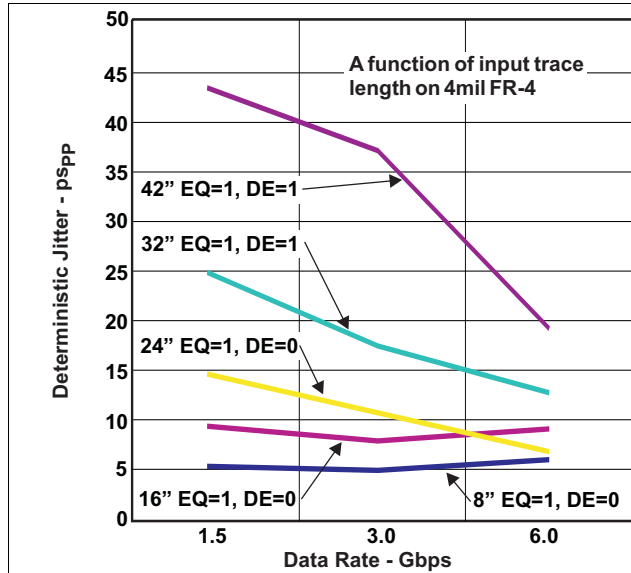


Figure 4. Deterministic Jitter vs Data Rate

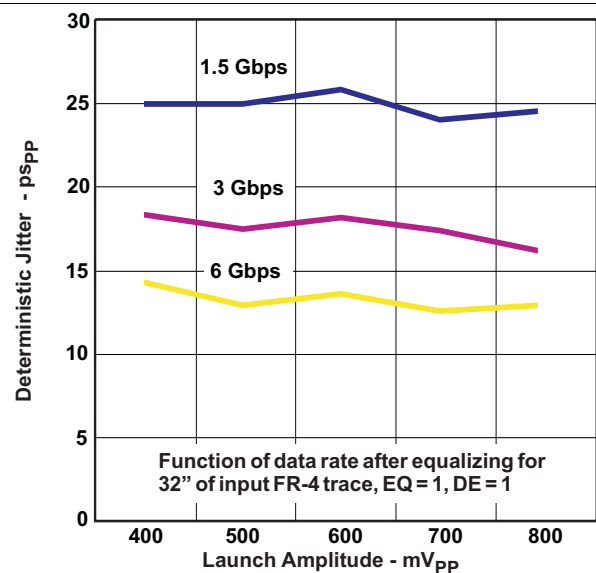


Figure 5. Deterministic Jitter vs Launch Amplitude

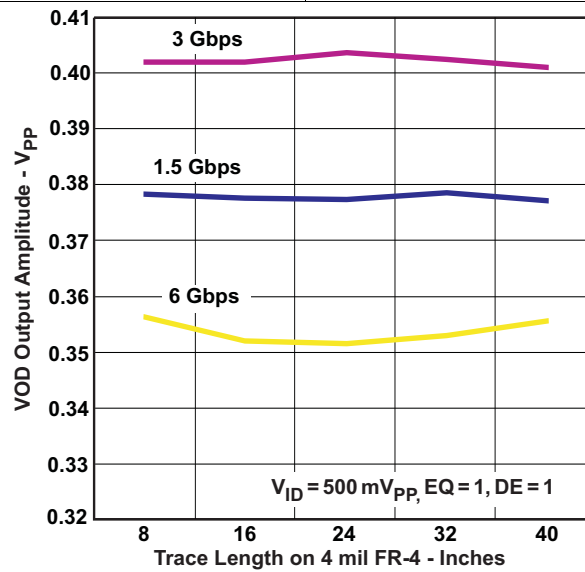


Figure 6. VOD Output Amplitude vs Trace Length

## 8 Parameter Measurement Information

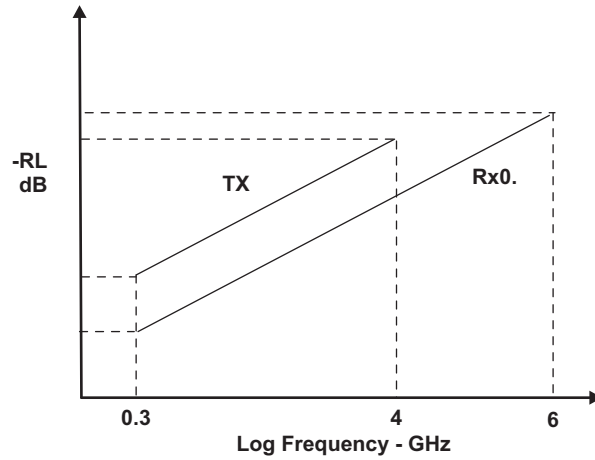


Figure 7. TX, RX Differential Return Loss Limits

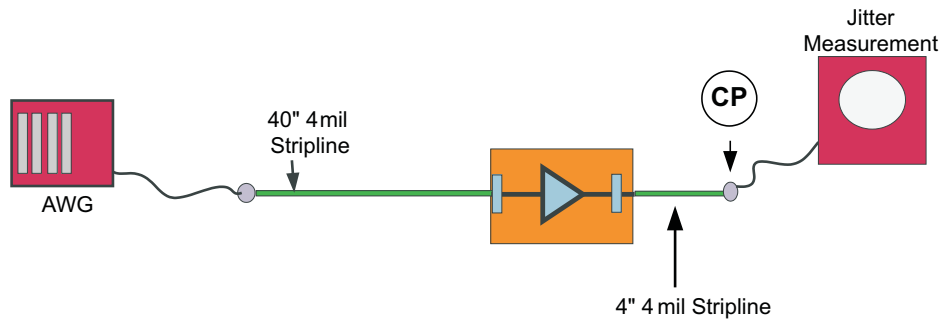


Figure 8. Jitter Measurement Test Condition

## 9 Detailed Description

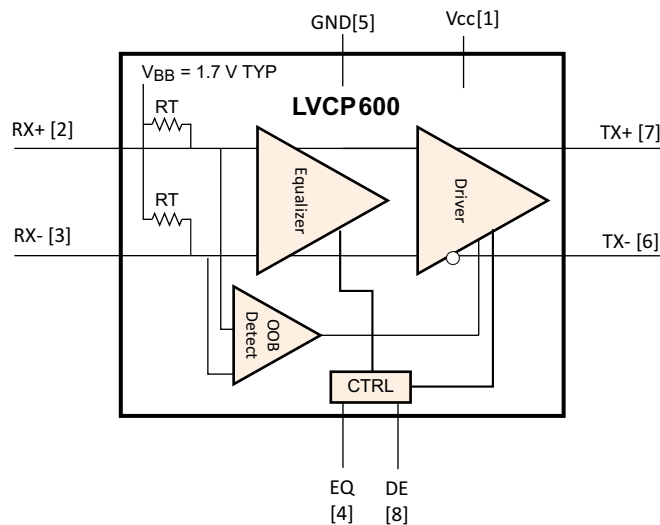
### 9.1 Overview

The SN75LVCP600 is a single-channel, SATA Express, and PCIe signal conditioner supporting data rates up to 6 Gbps. The device supports SATA Gen 1, 2, and 3 specifications as well as PCIe 1, 2, and 3. The SN75LVCP600 operates from a single 3.3-V supply and has 100-Ω line termination with self-biasing feature, making the device suitable for AC coupling. The inputs incorporate an out-of-band (OOB) detector, which automatically squelches the output when the input differential voltage falls below threshold while maintaining a stable common-mode voltage. The device is also designed to handle spread spectrum clocking (SSC) transmission per SATA standard. The SN75LVCP600 handles interconnect losses at its input with selectable equalization settings that are programmable to match the loss in the channel.

For data rates of 3 Gbps and lower the SN75LVCP600 equalizes signals for a span of up to 50 inches of FR4. For data rates of 8 Gbps the device compensates up to 40 inches of FR4.

The device is hot-plug capable preventing device damage under device *hot*-insertion such as async signal plug or removal, unpowered plug or removal, powered plug or removal, or surprise plug or removal.

### 9.2 Functional Block Diagram



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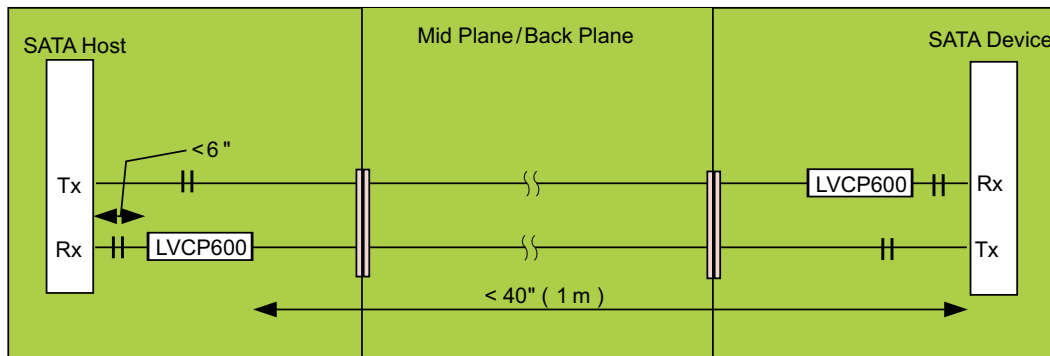
### 9.3 Feature Description

#### 9.3.1 Input Equalization

The SN75LVCP600 supports programmable equalization in its front stage; [Table 1](#) lists the equalization settings. The input equalizer is designed to recover a signal even when no eye is present at the receiver and effectively supports FR4 trace at the input anywhere from 4" to 40" at SATA 6G speed.

**Table 1. EQ and DE Settings**

EQ	EQUALIZATION (at 6 Gbps)	DE	DE-EMPHASIS (at 6 Gbps)
0 (default)	7 dB	0 (default)	0 dB
1	14 dB	1	-1.2 dB


**Note:**

Trace lengths are suggested values based on TI HSPICE simulations (done over programmable limits of input EQ) to meet SATA loss and jitter spec.

Actual trace length supported by the LVCP600 may be more or less than suggested values and will depend on board layout, trace widths and number of connectors used in the high speed signal path.

**Figure 9. Trace Length Example**

### 9.3.2 Auto Low Power (ALP) Mode

Auto Low Power (ALP) Mode is triggered when a channel is in the electrical idle state for  $> 10 \mu\text{s}$ . The device enters and exits Low Power Mode by actively monitoring input signal ( $V_{ID_{pp}}$ ) level. When the input signal is in the electrical idle state, that is,  $V_{ID_{pp}} < 50 \text{ mV}$  and stays in this state for  $> 10 \mu\text{s}$ , the device automatically enters the low power state. In this state the output is driven to VCM and the device selectively shuts off internal circuitry to lower power by  $> 90\%$  of its normal operating power. While in ALP mode the device continues actively to monitor input signal levels. When the input signal exceeds the SATA OOB upper threshold level, the device reverts to the active state. Exit time from Auto Low Power Mode is  $< 50 \text{ ns}$  (maximum). See [Auto Low Power](#).

### 9.3.3 Out-of-Band (OOB) Support

The squelch detector circuit within the device enables full detection of OOB signaling as specified in the SATA spec. When differential signal amplitude at the receiver input is  $50 \text{ mV}_{pp}$  or less, the output is squelched. Differential signal amplitude of  $90 \text{ mV}_{pp}$  or more is detected as an activity and therefore passed to the output indicating activity. Squelch circuit ON/OFF time is  $5 \text{ ns}$  (maximum). While in squelch mode outputs are held to VCM.

## 9.4 Device Functional Modes

### 9.4.1 Active

Active mode is the normal operating mode. When power is applied to the device, and the differential input signal to the receiver is greater than  $90 \text{ mV}_{pp}$ , the device is in active mode and meets all the specifications in the data sheet.

### 9.4.2 Squelch

When the device is powered, and the differential input signal to the receiver is less than  $50 \text{ mV}_{pp}$ , the device is in squelch mode. In squelch mode the transmitter outputs are both set to  $V_{CM_{TX}}$  or  $1.7 \text{ V}$ .

### 9.4.3 Auto Low Power

When the device is powered and the differential input signal to the receiver has been less than  $50 \text{ mV}_{pp}$  for greater than  $10 \text{ ns}$ , the device transitions to Auto Low Power (ALP) mode. In ALP, the transmitter outputs are both set to  $V_{CM_{TX}}$ . In addition, while in ALP, the device shuts off internal circuitry to lower power to less than 10% of the power in the Active mode.

## 10 Application and Implementation

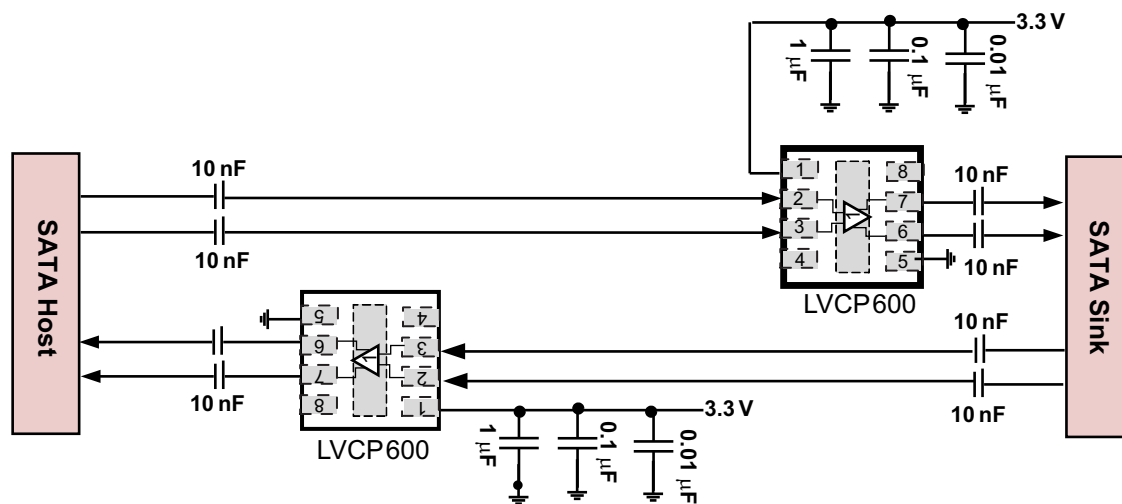
### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 10.1 Application Information

The SN75LVCP600 is a single-channel SATA redriver and signal conditioner supporting data rates up to 6 Gbps. The inputs incorporate an out-of-band (OOB) detector, which automatically squelches the output while maintaining a stable common-mode voltage compliant to the SATA link.

### 10.2 Typical Application



#### Note:

- 1) Place supply caps close to device pin
- 2) EQ and DE selection at 7 dB and 0dB respectively
- 3) Actual EQ /DE settings will depend on device placement relative to host and SATA connector

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**Figure 10. Typical Device Implementation**

#### 10.2.1 Design Requirements

This design requires layout flexibility to place 0-Ω resistors. If a redriver is needed, go to step 3 in [Detailed Design Procedure](#).

**Table 2. Design Parameters**

DESIGN PARAMETER	VALUE
$V_{CC}$	3.3 V
$I_{CC}$	29 mA
Input voltage	120 mV <sub>pp</sub> to 1.6 V <sub>pp</sub>
Output voltage	400 mV <sub>pp</sub> to 900 mV <sub>pp</sub>

### 10.2.2 Detailed Design Procedure

The LVCP600 allows the user to take the guess work of using a signal conditioning device in a SATA link. With the SN75LVCP600, the user has the option to use or remove the device based on signal conditioning needs. See [Figure 11](#).

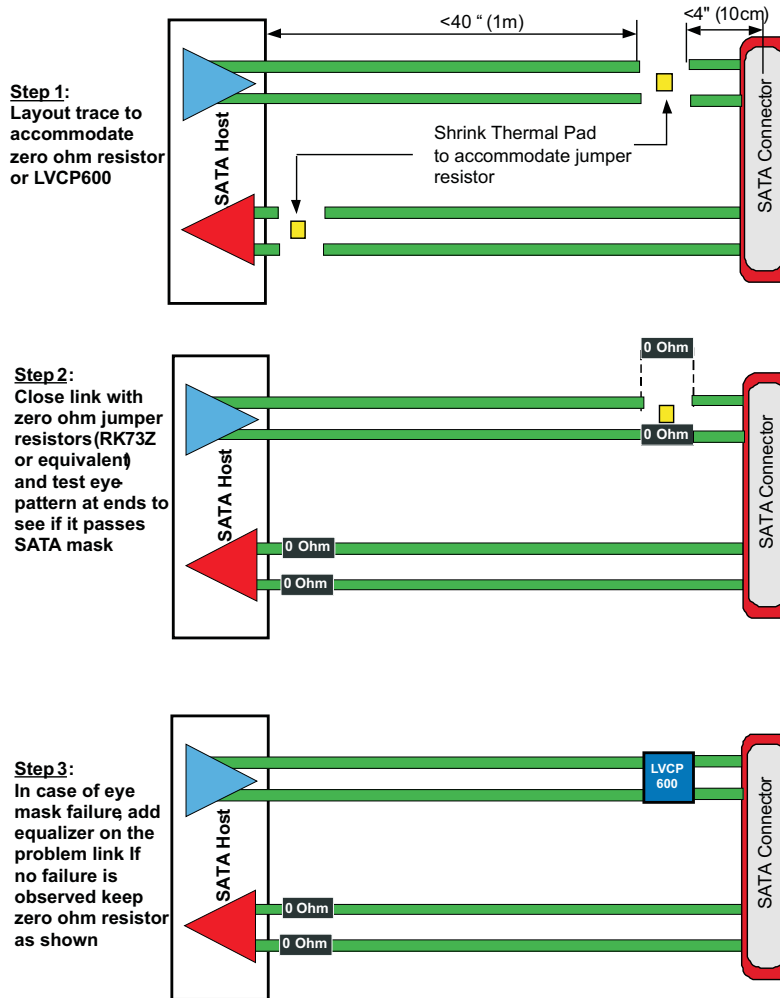


Figure 11. Implementation Guideline

[Figure 13](#) through [Figure 22](#) show SN75LVCP600 typical performance plots when connected to various trace lengths with  $V_{CC} = 3.3\text{ V}$  and  $T_A = 25^\circ\text{C}$ . All eye diagrams measured using K28.5 pattern at 6 Gbps. [Figure 12](#) shows the setup for the performance plots in [Application Curves](#).

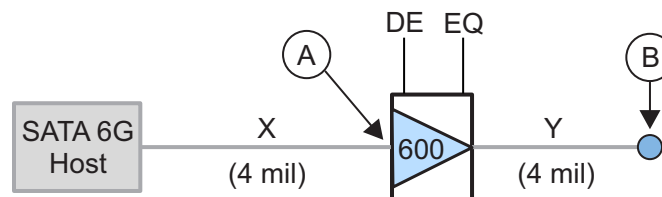


Figure 12. Test Points

10.2.3 Application Curves

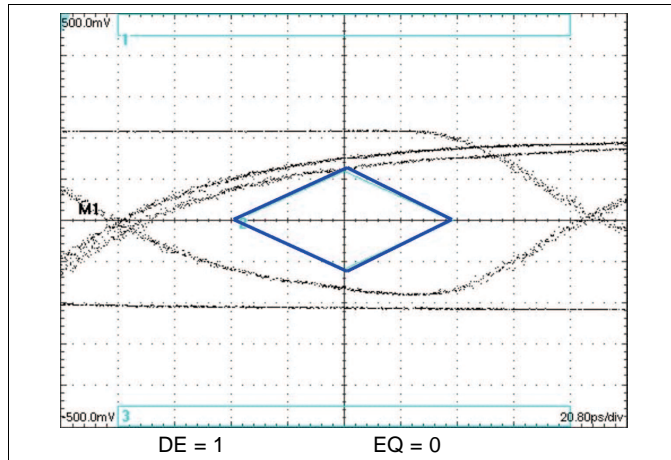


Figure 13. Eye Pattern at A → X = 8"; Y = 2"

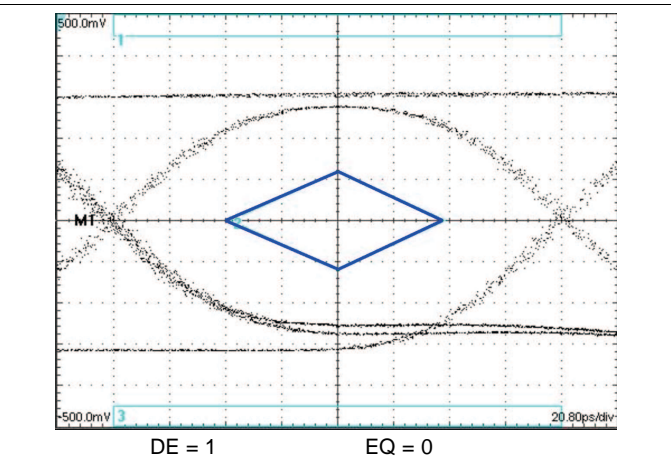


Figure 14. Eye Pattern at B → X = 8"; Y = 2"

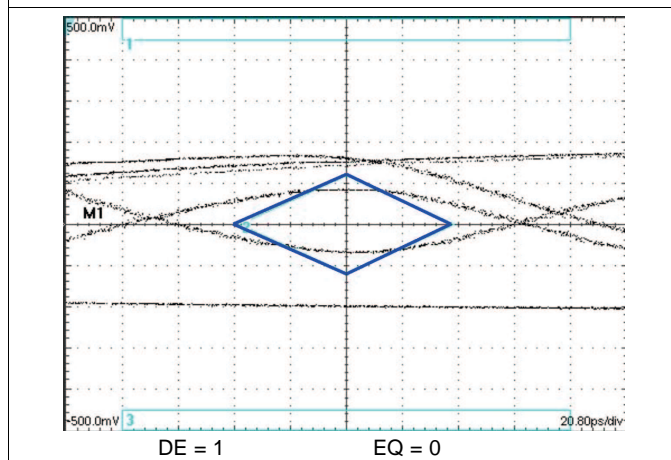


Figure 15. Eye Pattern at A → X = 16"; Y = 2"

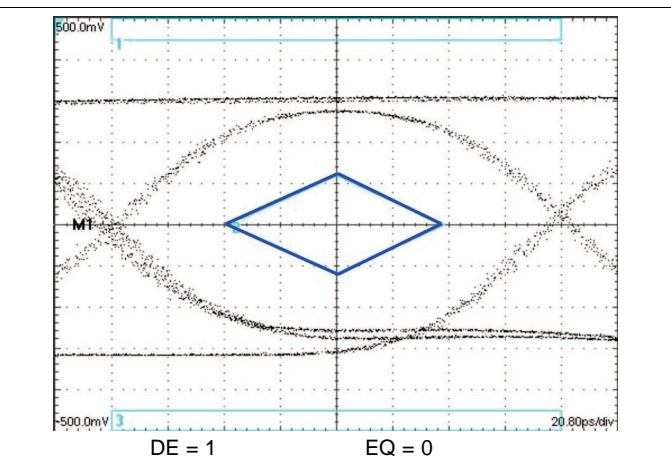


Figure 16. Eye Pattern at B → X = 16"; Y = 2"

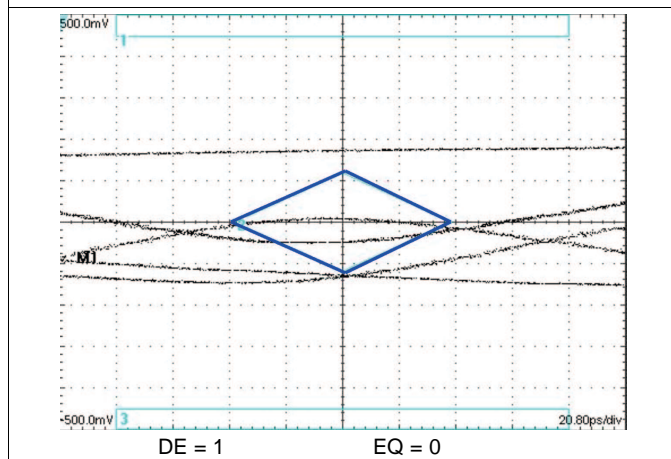


Figure 17. Eye Pattern at A → X = 24"; Y = 2"

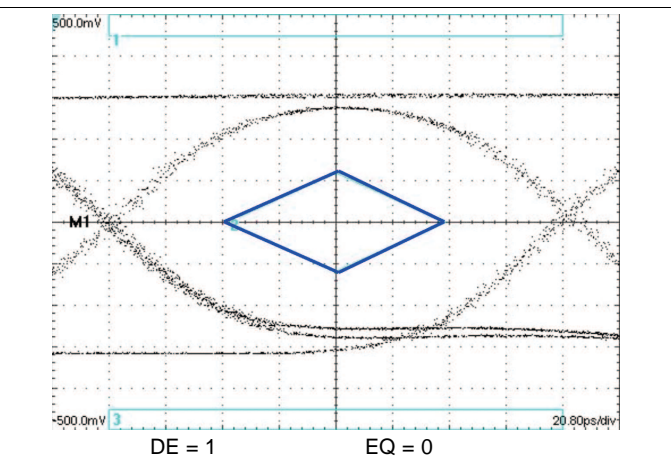


Figure 18. Eye Pattern at B → X = 24"; Y = 2"

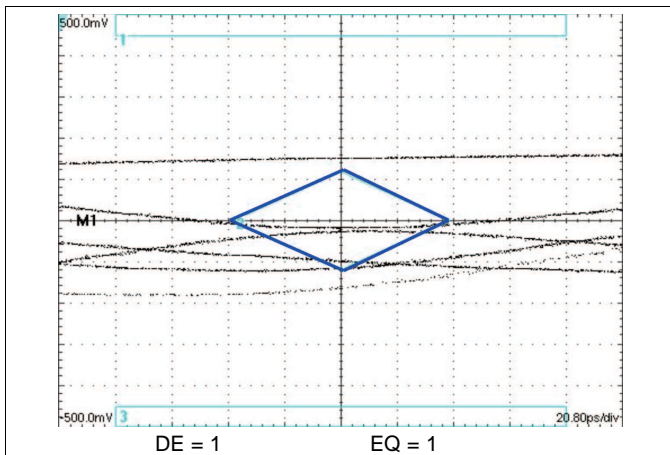


Figure 19. Eye Pattern at A → X = 32"; Y = 2"

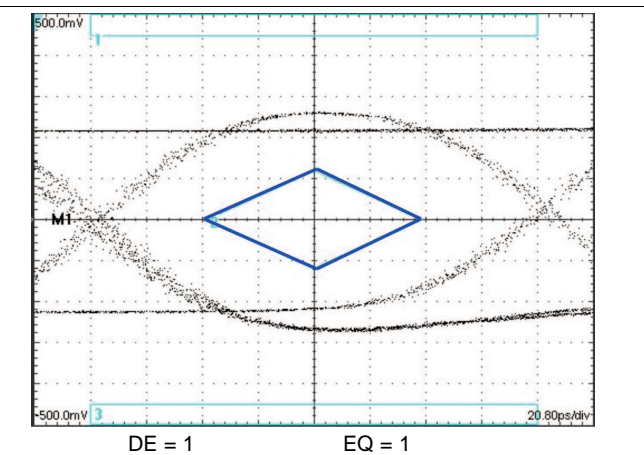


Figure 20. Eye Pattern at B → X = 32"; Y = 2"

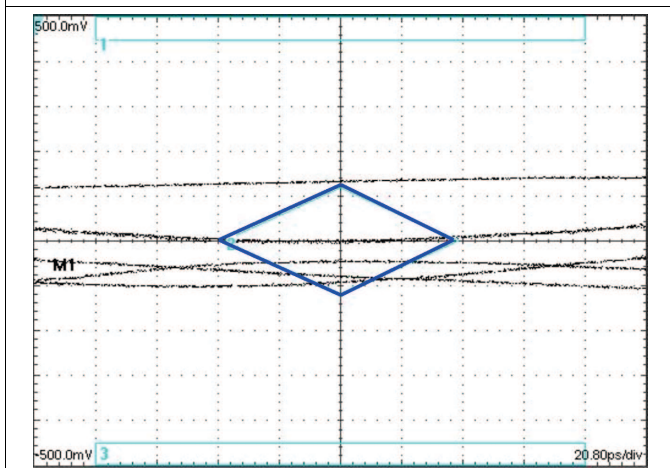


Figure 21. Eye Pattern at A → X = 40"; Y = 2"

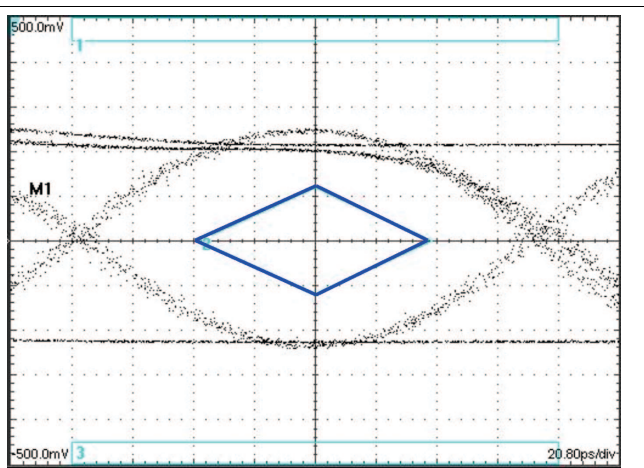


Figure 22. Eye Pattern at B → X = 40"; Y = 2"

## 11 Power Supply Recommendations

The SN75LVCP600 is designed to operate from a single 3.3-V supply. Always practice proper power-supply sequencing procedure. Apply  $V_{CC}$  first before any input signals are applied to the device. The power-down sequence is in reverse order.

## 12 Layout

### 12.1 Layout Guidelines

#### 12.1.1 Return Current and Plane References

High frequency return signal/current is defined as the path that a signal follows back to its original source as all signals flow in a closed loop. Minimizing the loop area of the closed loop is beneficial for both EMI (Electro-Magnetic Interference) reduction and signal integrity.

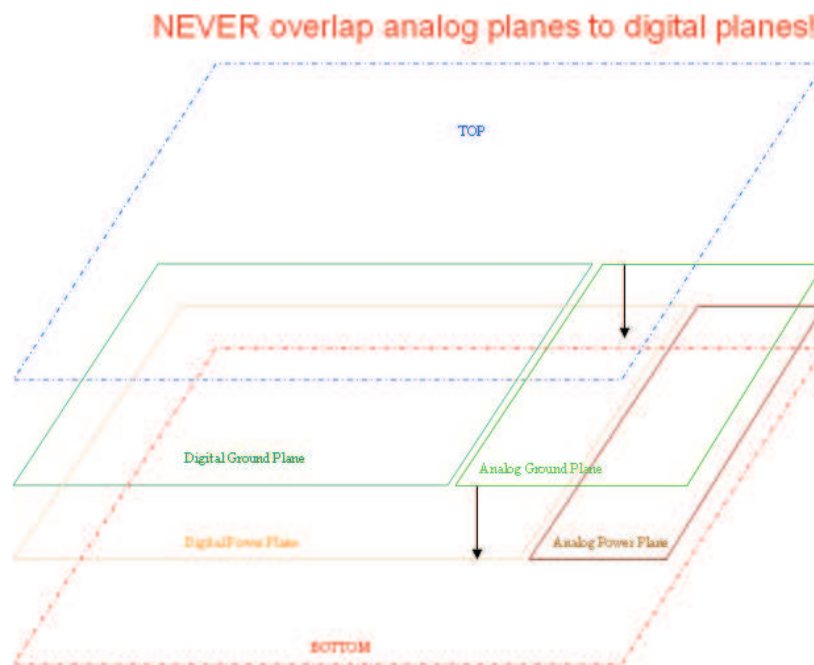
The best way to minimize loop area is to always have a signal reference their nearest solid ground or power plane. Obstructions to the return signal causes signal integrity problems like reflections, crosstalk, undershoot and overshoot.

Signals can reference either power or ground planes, but ground is preferred. Without solid plane references, single ended and differential impedance control is very hard to accomplish; crosstalk to other signals may happen as the return signals have no other path. This type of crosstalk is difficult to troubleshoot.

Symmetric pairing of solid planes in the layer stackup can significantly reduce warping of the PCB during the manufacturing process. Warping of the PCB is crucial to minimize on boards that uses BGA components.

#### 12.1.2 Split Planes – What to Avoid

Never route signals over splits in their perspective reference planes.



**Figure 23. Overlapping Analog and Digital Planes**

Layout Guidelines (continued)

This type of routing will compromise signal integrity!!

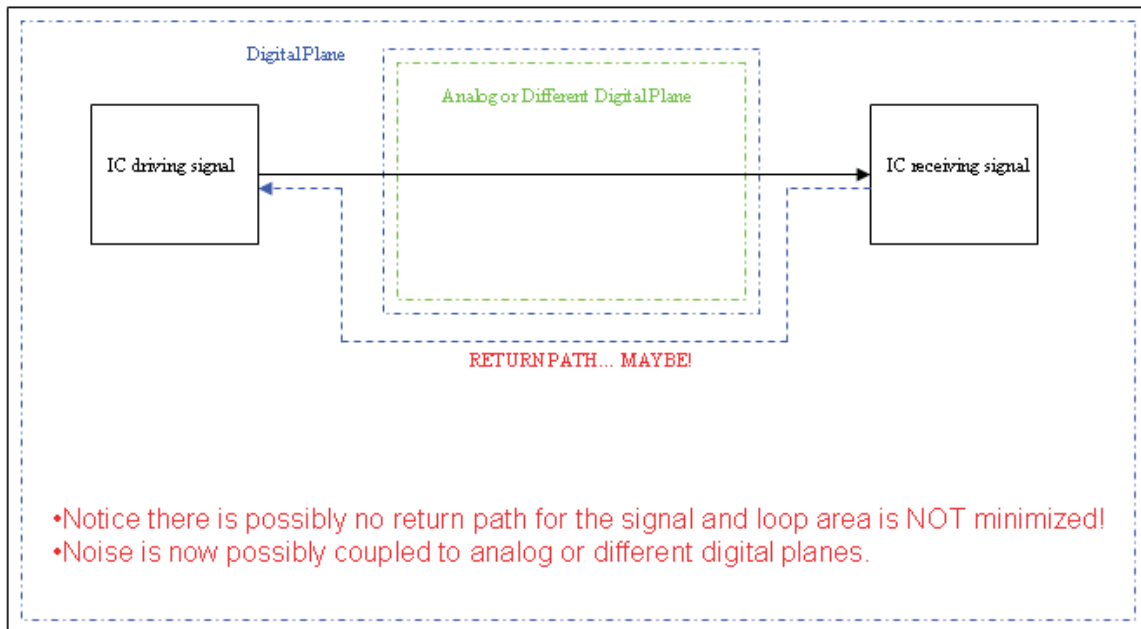


Figure 24. Incorrect Routing

Proper way to route AROUND splits in planes

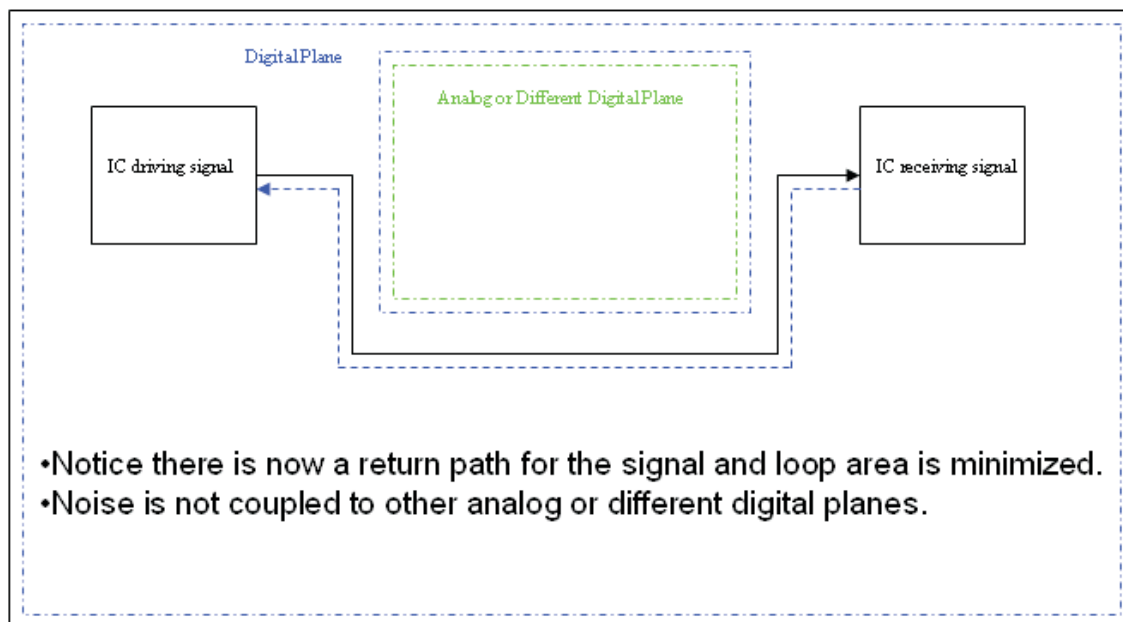


Figure 25. Proper Routing

## Layout Guidelines (continued)

### 12.1.3 Avoiding Crosstalk

Crosstalk is defined as interference from one trace to another by either or both inductive and capacitive coupling. Best ways to avoid crosstalk are:

- Provide stable reference planes for all high speed signals (as noted in previous sections).
- Use the 3W rule (3 times the width of trace for separation) where applicable on all signals, but absolutely use on clock signals.
- Use ground traces/guards around either *victim* or *aggressor* signals prone to crosstalk.
- When space is constrained and limited on areas of the PCB to route parallel buses, series or end termination resistors can be used to route traces closer than what is normally recommended. However, calculations and simulations must be done to validate the use of series or end termination resistors to eliminate crosstalk.

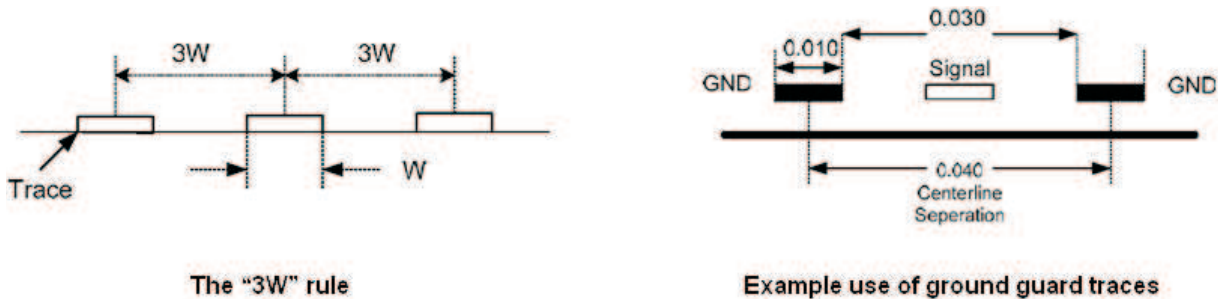


Figure 26. Ways to Avoid Crosstalk

## 12.2 Layout Example

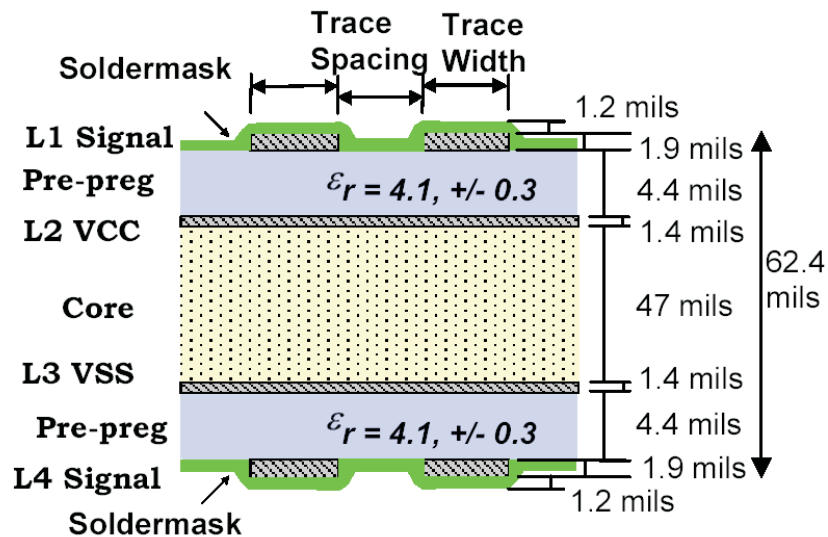


Figure 27. Printed-Circuit Board Stackup (FR-4 Example)

**Layout Example (continued)**

**4 Layer**

Layer 1	(Top)
Layer 2	(GND)
Layer 3	(PWR)
Layer 4	(Bottom)

**6 Layer**

Layer 1	(Top)
Layer 2	(GND)
Layer 3	(Signal)
Layer 4	(Signal)
Layer 5	(PWR)
Layer 6	(Bottom)

**10 Layer**

Layer 1	(Top)
Layer 2	(GND)
Layer 3	(Signal)
Layer 4	(Signal)
Layer 5	(PWR)
Layer 6	(GND)
Layer 7	(Signal)
Layer 8	(Signal)
Layer 9	(GND)
Layer 10	(Bottom)

PCB layer configuration suggestions for stackup symmetry and signal integrity.

**Figure 28. PCB Layer Configuration Suggestions**

## 13 Device and Documentation Support

### 13.1 Device Support

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ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

#### 13.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
SN75LVCP600DRFR	ACTIVE	WSON	DRF	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 85	600	<a href="#">Samples</a>
SN75LVCP600DRFT	ACTIVE	WSON	DRF	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	0 to 85	600	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**TAPE AND REEL INFORMATION**

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75LVCP600DRFR	WSON	DRF	8	3000	180.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2
SN75LVCP600DRFT	WSON	DRF	8	250	180.0	8.4	2.3	2.3	1.15	4.0	8.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75LVCP600DRFR	WSON	DRF	8	3000	210.0	185.0	35.0
SN75LVCP600DRFT	WSON	DRF	8	250	210.0	185.0	35.0

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